

SN54AHCT157, SN74AHCT157 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS347K – MAY 1996 – REVISED JULY 2003

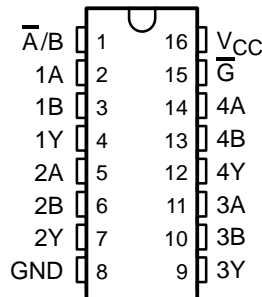
- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17

description/ordering information

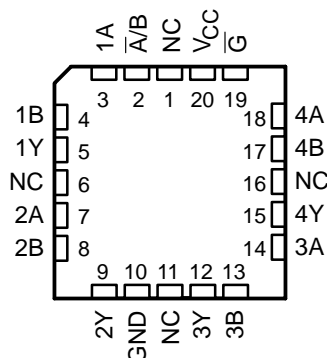
These quadruple 2-line to 1-line data selectors/multiplexers are designed for 4.5-V to 5.5-V V_{CC} operation.

The 'AHCT157 devices feature a common strobe (\overline{G}) input. When the strobe is high, all outputs are low. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. The devices provide true data.

SN54AHCT157 . . . J OR W PACKAGE SN74AHCT157 . . . D, DB, DGV, N, NS, OR PW PACKAGE (TOP VIEW)



SN54AHCT157 . . . FK PACKAGE (TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AHCT157N	SN74AHCT157N
	SOIC – D	Tube	SN74AHCT157D	AHCT157
		Tape and reel	SN74AHCT157DR	
	SOP – NS	Tape and reel	SN74AHCT157NSR	AHCT157
	SSOP – DB	Tape and reel	SN74AHCT157DBR	HB157
	TSSOP – PW	Tube	SN74AHCT157PW	HB157
		Tape and reel	SN74AHCT157PWR	
TVSOP – DGV	Tape and reel	SN74AHCT157DGV	HB157	
–55°C to 125°C	CDIP – J	Tube	SNJ54AHCT157J	SNJ54AHCT157J
	CFP – W	Tube	SNJ54AHCT157W	SNJ54AHCT157W
	LCCC – FK	Tube	SNJ54AHCT157K	SNJ54AHCT157FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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 **TEXAS
INSTRUMENTS**

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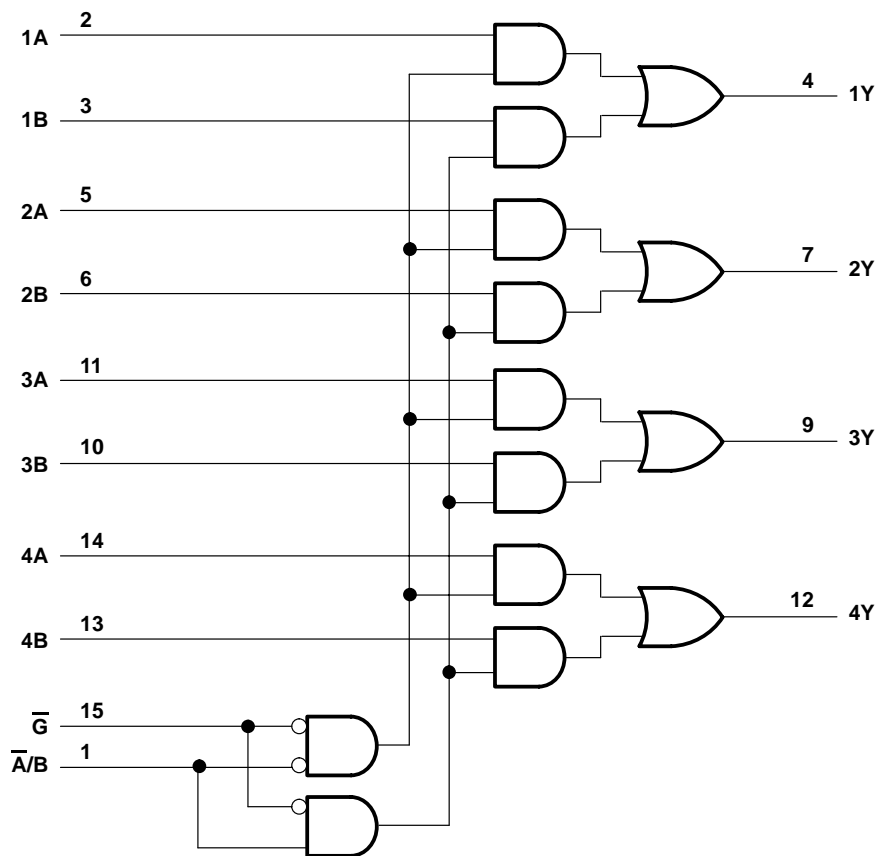
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FUNCTION TABLE

INPUTS				OUTPUT Y
\bar{G}	$\bar{A/B}$	A	B	
H	X	X	X	L
L	L	L	X	L
L	L	H	X	H
L	H	X	L	L
L	H	X	H	H

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, and W packages.



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SN54AHCT157, SN74AHCT157 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Output voltage range, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	73°C/W
DB package	82°C/W
DGV package	120°C/W
N package	67°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

	SN54AHCT157		SN74AHCT157		UNIT
	MIN	MAX	MIN	MAX	
V_{CC} Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH} High-level input voltage	2		2		V
V_{IL} Low-level input voltage		0.8		0.8	V
V_I Input voltage	0	5.5	0	5.5	V
V_O Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH} High-level output current		–8		–8	mA
I_{OL} Low-level output current		8		8	mA
$\Delta t/\Delta v$ Input transition rise or fall time		20		20	ns/V
T_A Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHCT157		SN74AHCT157		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	4.5 V	4.4	4.5		4.4		4.4	V	
	I _{OH} = -8 mA		3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 μA	4.5 V			0.1			0.1	V	
	I _{OL} = 8 mA				0.36		0.44	0.44		
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1			±1	μA	
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			2		20	20	μA	
ΔI _{CC} †	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35		1.5	1.5	mA	
C _i	V _I = V _{CC} or GND	5 V		2	10			10	pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHCT157		SN74AHCT157		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	Y	C _L = 15 pF	4.1**	6.4**		1**	7.5**	1	7.5	ns
t _{PHL}				4.1**	6.4**	1**	7.5**	1	7.5		
t _{PLH}	A̅/B	Y	C _L = 15 pF	5.3**	8.1**		1**	9.5**	1	9.5	ns
t _{PHL}				5.3**	8.1**	1**	9.5**	1	9.5		
t _{PLH}	G̅	Y	C _L = 15 pF	5.6**	8.6**		1**	10**	1	10	ns
t _{PHL}				5.6**	8.6**	1**	10**	1	10		
t _{PLH}	A or B	Y	C _L = 50 pF	5.6	8.7		1	10.8	1	9.8	ns
t _{PHL}				5.6	8.7	1	10.8	1	9.8		
t _{PLH}	A̅/B	Y	C _L = 50 pF	6.8	10.4		1	13.2	1	12	ns
t _{PHL}				6.8	10.4	1	13.2	1	12		
t _{PLH}	G̅	Y	C _L = 50 pF	7.1	11		1	13.5	1	12	ns
t _{PHL}				7.1	11	1	13.5	1	12		

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

PARAMETER		SN74AHCT157			UNIT
		MIN	TYP	MAX	
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.4	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.4	-0.8	V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		4.8		V
V _{IH(D)}	High-level dynamic input voltage	2			V
V _{IL(D)}	Low-level dynamic input voltage			0.8	V

NOTE 4: Characteristics are for surface-mount packages only.

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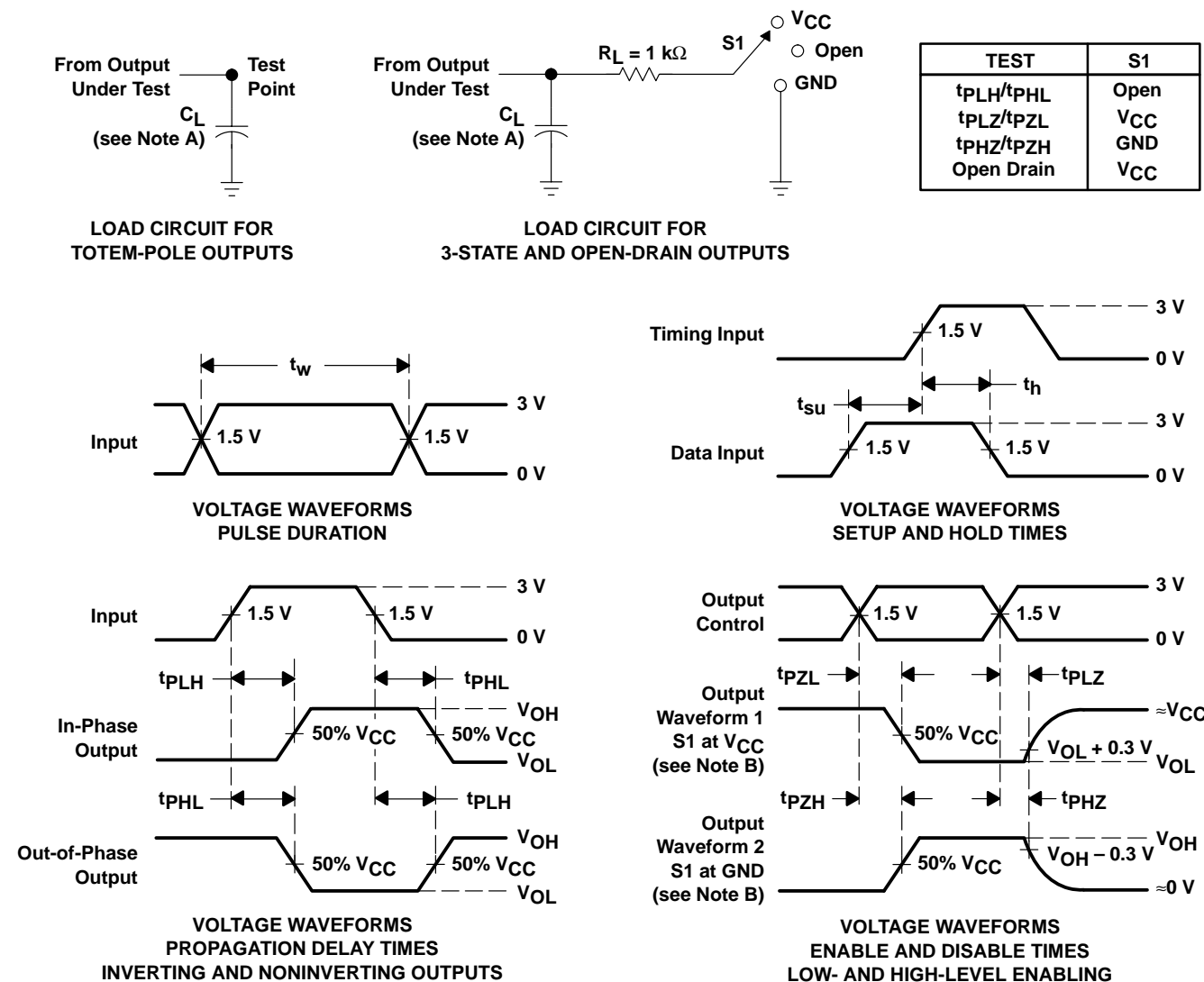
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operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	11	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AHCT157D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DBLE	OBSOLETE	SSOP	DB	16		TBD	Call TI	Call TI
SN74AHCT157DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DBG4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DGV	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DGVRE4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DGVRG4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHCT157NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHCT157NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PWLE	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI
SN74AHCT157PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT157PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

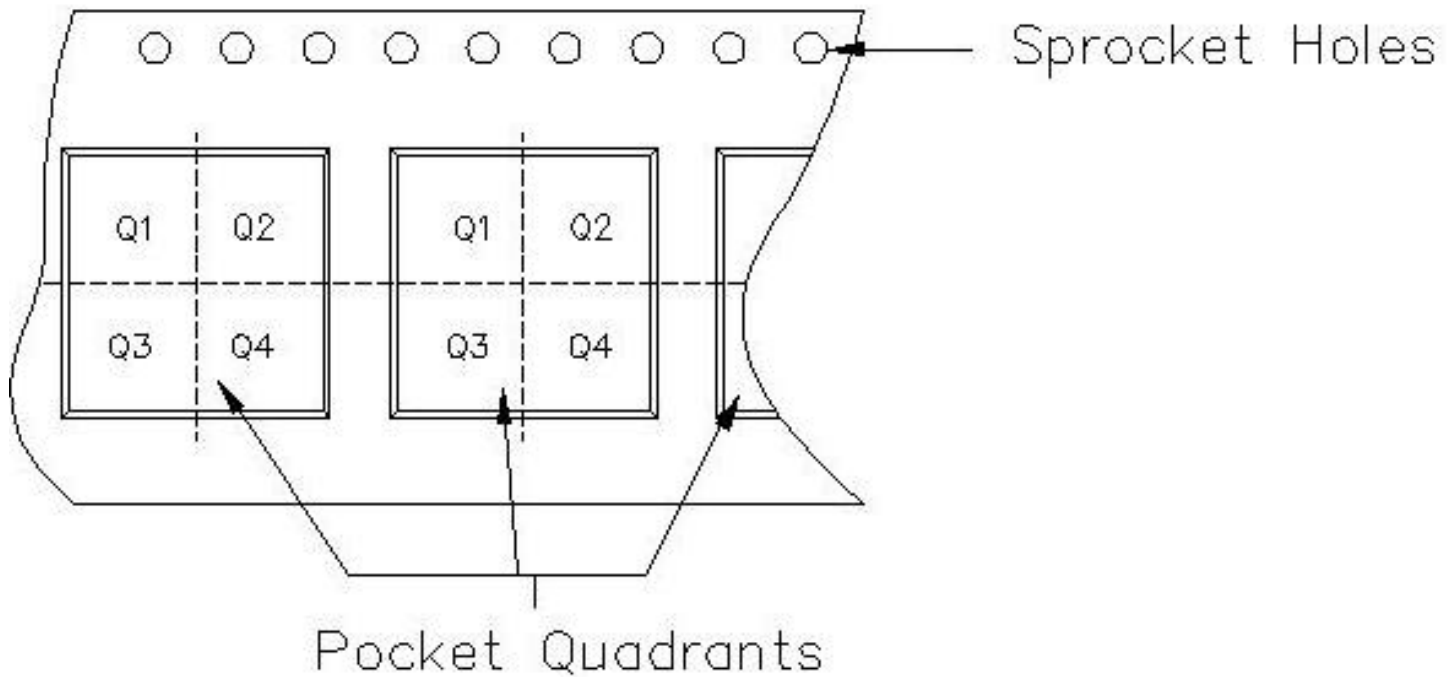
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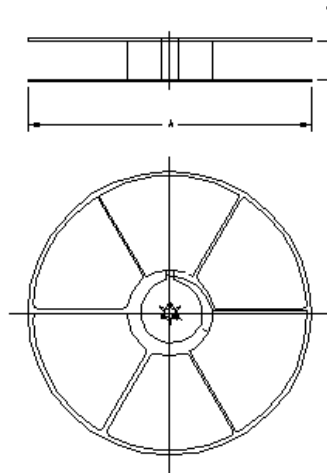
Carrier tape design is defined largely by the component length, width, and thickness.

A_o = Dimension designed to accommodate the component width.
B_o = Dimension designed to accommodate the component length.
K_o = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



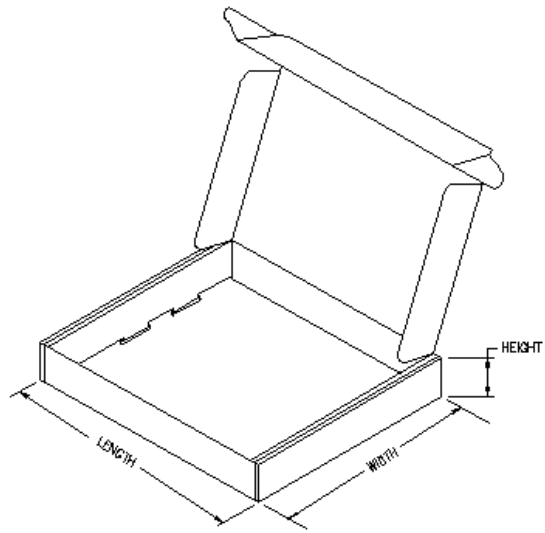
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT157DBR	DB	16	MLA	330	16	8.2	6.6	2.5	12	16	Q1
SN74AHCT157DGVR	DGV	16	MLA	330	12	6.8	4.0	1.6	8	16	Q1
SN74AHCT157DR	D	16	FMX	330	16	6.5	10.3	2.1	8	16	Q1
SN74AHCT157NSR	NS	16	MLA	330	16	8.2	10.5	2.5	12	16	Q1
SN74AHCT157PWR	PW	16	MLA	330	12	7.0	5.6	1.6	8	12	Q1



TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74AHCT157DBR	DB	16	MLA	346.0	346.0	33.0
SN74AHCT157DGVR	DGV	16	MLA	346.0	346.0	29.0
SN74AHCT157DR	D	16	FMX	342.9	336.6	28.58
SN74AHCT157NSR	NS	16	MLA	346.0	346.0	33.0
SN74AHCT157PWR	PW	16	MLA	346.0	346.0	29.0



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - (C) Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - (D) The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - \triangle Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - \triangle Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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